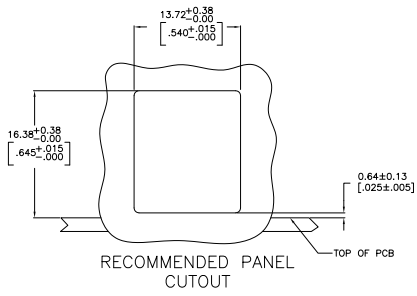
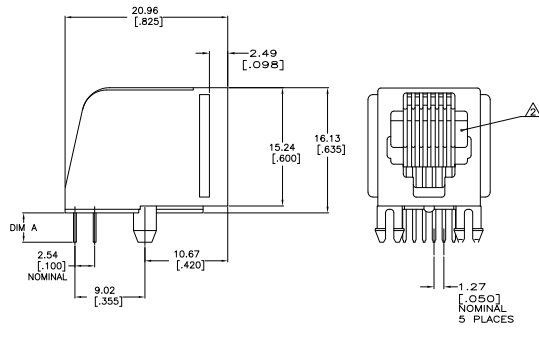
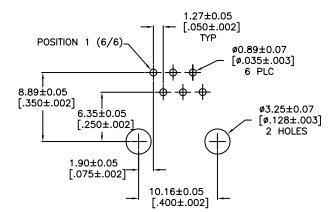
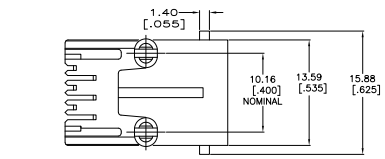


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REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00				
DT		REVISED PER EDD-11-005140	28MAR11	RK	HMR



- MATERIAL:
 HOUSING - PBT POLYESTER, COLOR: BLACK
 TERMINAL - 0.36[014] THICK PHOS. BRONZE PLATED
 WITH (SEE TABLE) MIN HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 2.03µm[000080] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[000050] MIN THICK NICKEL UNDERPLATE
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 0.15µm[000006] GOLD PLATED PARTS DO NOT MEET THE MINIMUM GOLD THICKNESS REQUIREMENT OF FCC SPECIFICATION, PART 68. PARTS HAVE NOT BEEN TESTED TO THE DURABILITY REQUIREMENTS OF TE PRODUCT SPEC 108-1163
- TERMINALS FOR 5520250-1, -2, -11 AND -22 LOCATED IN CENTER POSITIONS
- DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN

GOLD THICKNESS	DIM A	TERMINALS REQUIRED	PART NUMBER
0.15µm[000006]	3.30-4.32 [1.30-1.70]	6	2-5520250-3
		4	2-5520250-2
	2.18-2.67 [0.85-1.05]	4	1-5520250-1
1.27µm[000050]	3.30-4.32 [1.30-1.70]	6	5520250-3
		4	5520250-2
		2	5520250-1

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TE Connectivity
 MODULAR JACK ASSEMBLY,
 6 POSITION, SIDE ENTRY, FLANGELESS,
 WITH PANEL STOPS

REV: 1
 DATE: 108-1163
 REV: 2
 DATE: 114-2048
 REV: 3
 DATE: 114-2048

SEE NOTE 1
 SEE NOTE 1
 SEE NOTE 1

CUSTOMER DRAWING
 DATE: 4.1
 SHEET: 1
 OF: 1
 DT